MPI2520

High Current, Low Profile, Miniature Power Inductors







Applications:

- Mobile/smart phones
- Handheld/mobile equipment
- Digital cameras
- Media players
- MP3 Plave 's
- Tublet 1/e readers

Env ronmental data:

- Storage temperature range (Component): -40°C to +125°C
 - Operating temperature 131 ge. -40°C to +125°C (ambient + self + ;m, p, rature rise)
- Solder re 100 tomperature: J-STD-020D com lian

c 'a rizig:

Supplied in tape and reel packaging, 3000 parts per 7" diameter reel

Produc description:

- Discontini Septemi Halogen free, lead free RoHS compliant
 - 125°C n a rim um total temperature
 - 2.7 x 2.2 x 1.77 1.2mm maximum surface mount package
 - ivlagnetically snielded, low EMI
 - Indi ctance range from 0.47μH to 10.0μH
 - Current range from 1.1 to 4.8 amps



Product specifications

Part Number ⁵	OCL1 (μH)±20%	I _{rms} ² (Amps)	I _{sat} ³ (Amps)	DCR (mΩ) @ 25°C typical	DCR (mΩ) @ 25°C max	K-Factor⁴	
R0 —1.0mm Height							
MPI2520R0-R47-R	0.47	4.1	4.4	28	34	2887	
MPI2520R0-1R0-R	0.9	3.2	3.2	50	60	1925	
MPI2520R0-1R5-R	1.5	2.4	2.6	80	96	1444	
MPI2520R0-2R2-R	2.2	2.2	2.4	103	124	1283	
MPI2520R0-3R3-R	3.3	1.6	1.6	190	228	1050	
MPI2520R0-4R7-R	4.7	1.4	1.4	240	288	825	
R1 - 1.2mm Height							
MPI2520R1-R47-R	0.47	4.5	4.8	20	24	2310	
MPI2520R1-1R0-R	1.0	3.7	4.0	35	42	1925	
MPI2520R1-1R5-R	1.5	2.9	5.3	55	66	1444	
MPI2520R1-2R2-R	2.2	2.3	2.7	7!	90	1255	
MPI2520R1-3R3-R	3.3	1.8	2.4	105	126	962	
MPI2520R1-4R7-R	4.7).(6)	C.S	150	180	925	
MPI2520R1-5R6-R	555	1.5	15	250	240	679	
MPI2520R1-6R8-R	6.8	1.3	1.3	300	360	679	
MPI2520R1-100-B	10.0	1.1	1.2	390	165	525	

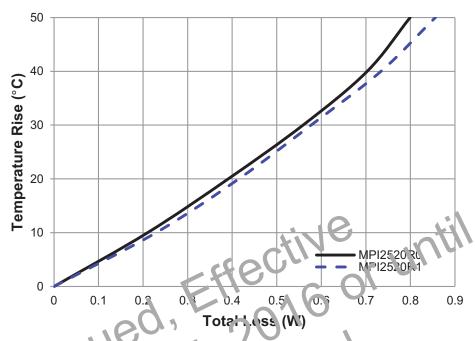
- 1. Ope. Circuit industance (OCL) Test Paramaters: in/Hz, 0.1Vrms, 0.0Ac , 2F C
 2. I_{ms}: Do current for an approximal temperature rise of 40°C without ore loss. Derating is necessity for 2 currents. PCB layout trace this Reconers not exceed 195% under worst case upe at 19 conditions verified in the end application.
- 3. I_{sat}: Peak current for approxir a sty 10% rolloff at +2!

- K-factor Us to to etermine B $_{pp}$ for core loss (see graph). B $_{pp}$ (K $_{L}$ * * * * * * (Gauss), K: (K-factor from table), L: (In uctance in $_{\mu}$ H), $_{L}$ (Peak to peak ripple current in Amps).
- art Number Definition: MPI2520Rx-yyy-R
 - MPI2520Rx = Product code and size
- yyy = Inductance value in μH , R = decimal point, if no R is present then third character = number of zeros.
- "-R" suffix = RoHS compliant

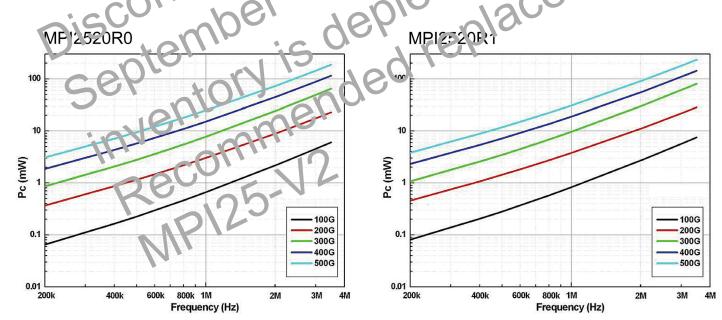
Dimensions - mm



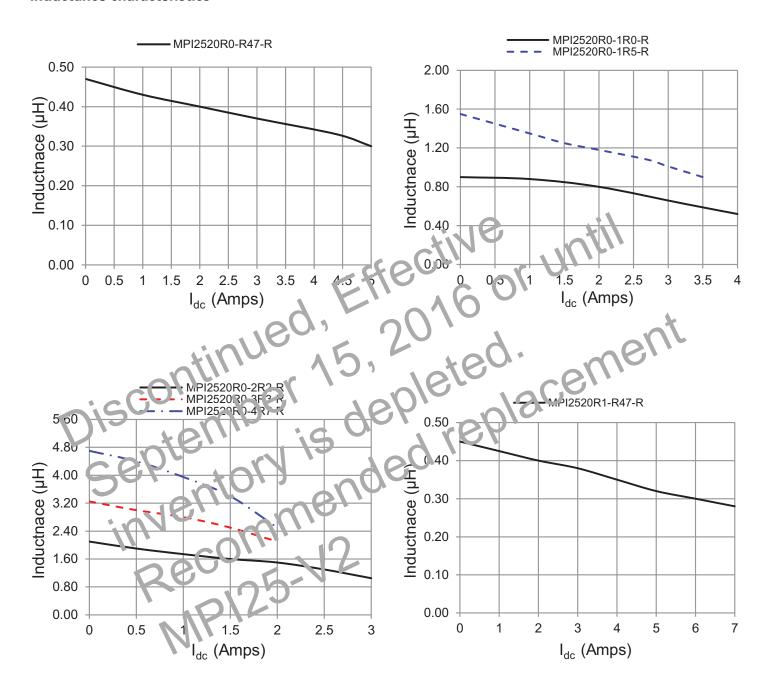
Temperature rise vs. total loss



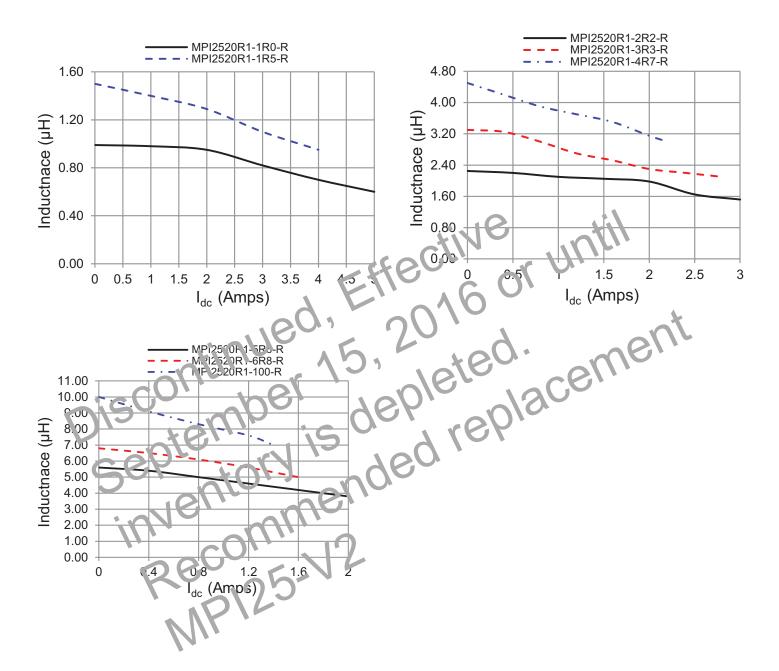




Inductance characteristics



Inductance characteristics



Solder reflow profile

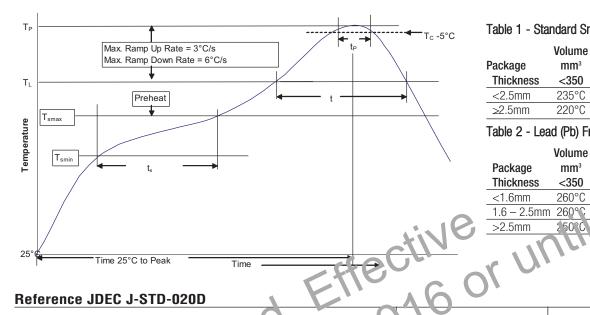


Table 1 - Standard SnPb Solder (T_c)

	Volume	Volume
Package	mm³	mm³
Thickness	<350	≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm ³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Slandard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak • Temperature min. 1 _{c,min})	100°C	150°C
• Ten pera ure max. (T _{smax})	50°C	200°C
● Tin e T _{smin} to T _{smax} (t _s)	60 120 Seconds	60-120 Seconds
Average ramp unital 3 T _{smax} to T _p	3°C/ Second h'a .	3°C/ Second Max.
Liquidous temperature (TL)	103 CO	217°C
Time at I quiaous (t _L)	60-150 <i>3</i> econds	60-150 Seconds
Peak package body tombe at re (Tp)*	Table 1	Table 2
Time $(t_p)^{**}$ vithin 5 °C of the specified classification temperature (Γ_c)	20 Seconds**	30 Seconds**
Average ramp fown rate (Tp to Tsm.x)	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temper ture	6 Minutes Max.	8 Minutes Max.
* Tolerance for peak prof e temperature (T_p) is defined as a supplier minimum an ** Tolerance for 'in e at peak profile tempe at the (T_p) is defined as a supplier minimum and the supplier (T_p) is defined as a supplier minimum and the supplier (T_p) is defined as a supplier minimum and the supplier (T_p) is defined as a supplier minimum and (T_p) is defined as a s		

^{*} Tolerance for peak pion f e temperature (T_p) is the ine f as a supplier minimum and a user maximum.

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^{**} Tolerance for 'in e at peak profile tempe at the (-p) is defined as a supplier minimum and a user maximum.